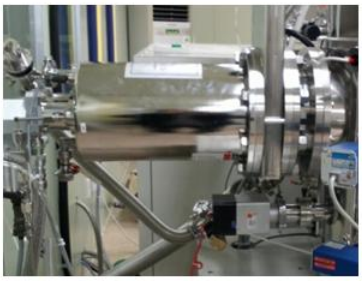
Super high speed Evaporator System
(초고속 진공 증착기)

Specification

Chamber

- Main Chamber : Rectangular Type
- Loading Chamber : Circular Type (Optional)
- Material : SUS 304
- Chamber internal shield cover (Easy exchange type)

Vacuum pump



- Turbo pump or Cryo Pump (Optional)
- Rotary pump (Optional : Dry pump)
- High Vacuum Gate Valve

Substrate

- Sample Size : Piece ~ 6″ Wafer (Etc Optional)
- Single sample Rotation Type (One process)
- Multi sample Rotation Type (One process)
- Rotation & Revolution Substrate (Optional)
- Substrate Shutter
- Rotation speed : 0 ~ 30 R.P.M
- Revolution speed : 0 ~ 30 R.P.M

Daedong
Hightechnologies

www.ddhightech.co.kr

master@ddhightech.co.kr

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Specification

Thickness Monitor

- Thickness Monitor or Controller (Optional)
- Rate Monitoring or Rate Control type
- Rate Resolution : Below than 0.1Å/Sec
- Single or Dual sensor mount type (Multi sensor is optional)
- Co-deposition available (Optional)
- Thickness sensor Shutter (Optional)
- Supply Brand (Inficon or Sycon)

Source & Power Supply

- Source : Induction Coil & Crucible (Optional)
- Crucible Size : 15cc ~ 100cc (Optional)
- Source Housing Water Cooling
- Induction Coil Water Cooling
- Induction Power Frequency : 10~30KHz
- Power Capacity : 10kW ~ Optional
- Inside water cooling
- Source Shutter

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Specification

Required Services	Main Power : 220V or 380V, 3 Phase, 50A
	PCW (Water) : 2~3kgf/Cm2
	Compressed Air : 5.5~6 Kgf/Cm2
	N2 Gas (Chamber Vent) : 1~2 Kgf/Cm2
	Exhaust : Ø40 Flexible Hose

Remark

Chamber Ultimate Pressure (One Chamber type)
; Below than 2 x 10^{-7}Torr

Pumping speed (One Chamber type) : Below than 5 x 10^{-6} Torr
; Below than 3 x 10^{-6} Torr (Within 30 Minute after Sample loading)

Film deposition Uniformity : Below than ±5%

Deposition Rate control range : 1Å/Sec ~ 1000Å/Sec
(Thin film ~ thick film control available)

Deposition Material : Cu, Al, Ag, etc Metal Process

Application

① **Fast thick film deposition process**
Deposition Rate : More than 1000Å/Sec

② Instead of wet **plating (Cu, Al, Ag, Cr, Ni, etc metal film)**

③ TSV (Through silicon via) Process